

## 60MSPS 10-bit 2-channel CCD Digitiser

### DESCRIPTION

The WM8216 is a 10-bit analogue front end/digitiser IC which processes and digitises the analogue output signals from CCD sensors or Contact Image Sensors (CIS) at pixel sample rates of up to 60MSPS.

The device includes two analogue signal processing channels each of which contains Reset Level Clamping, Correlated Double Sampling and Programmable Gain and Offset adjust functions. The output from each of these channels is time multiplexed into a single high-speed 10-bit Analogue to Digital Converter. The digital output data is available in 10-bit wide parallel format.

An internal 4-bit DAC is supplied for internal reference level generation. This may be used during CDS to reference CIS signals or during Clamping to clamp CCD signals. An external reference level may also be supplied. ADC references are generated internally, ensuring optimum performance from the device.

Using an analogue supply voltage of 3.3V and a digital interface supply of 3.3V, the WM8216 typically only consumes 330mW

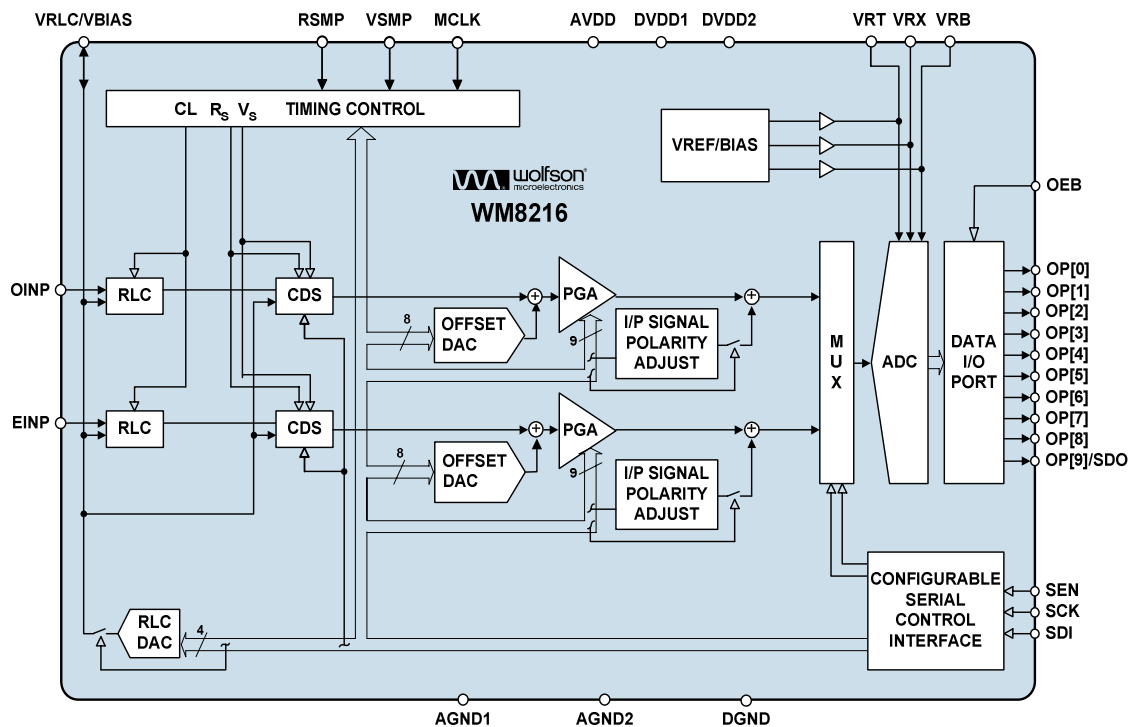
### FEATURES

- 10-bit ADC
- 60MSPS conversion rate
- Low power – 330mW typical
- 3.3V single supply operation
- Single or dual channel operation
- Correlated double sampling
- Programmable gain (9-bit resolution)
- Programmable offset adjust (8-bit resolution)
- Flexible clamp timing
- Programmable clamp voltage
- Internally generated voltage references
- 32-lead QFN package
- Serial control interface

### APPLICATIONS

- Digital Copiers
- USB2.0 compatible scanners
- Multi-function peripherals
- High-speed CCD/CIS sensor interface

### BLOCK DIAGRAM

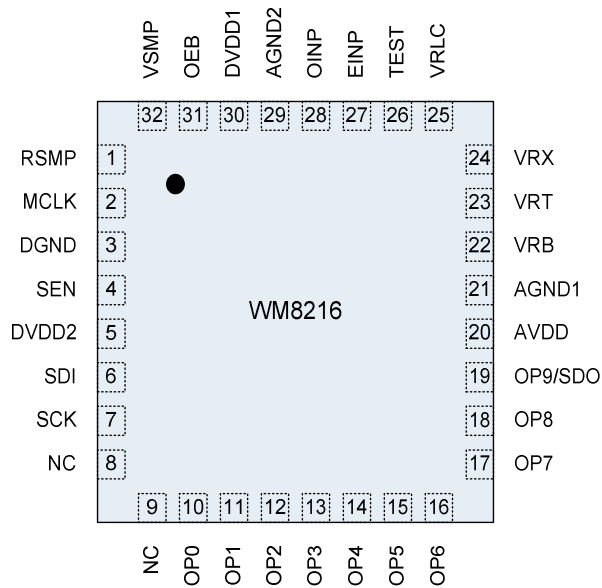


---

**TABLE OF CONTENTS**

<b>DESCRIPTION</b> .....	<b>1</b>
<b>FEATURES</b> .....	<b>1</b>
<b>APPLICATIONS</b> .....	<b>1</b>
<b>BLOCK DIAGRAM</b> .....	<b>1</b>
<b>TABLE OF CONTENTS</b> .....	<b>2</b>
<b>PIN CONFIGURATION</b> .....	<b>3</b>
<b>ORDERING INFORMATION</b> .....	<b>3</b>
<b>PIN DESCRIPTION</b> .....	<b>4</b>
<b>ABSOLUTE MAXIMUM RATINGS</b> .....	<b>5</b>
<b>RECOMMENDED OPERATING CONDITIONS</b> .....	<b>5</b>
<b>THERMAL PERFORMANCE</b> .....	<b>5</b>
<b>ELECTRICAL CHARACTERISTICS</b> .....	<b>6</b>
INPUT VIDEO SAMPLING .....	8
SERIAL INTERFACE.....	9
<b>INTERNAL POWER ON RESET CIRCUIT</b> .....	<b>11</b>
<b>DEVICE DESCRIPTION</b> .....	<b>13</b>
INTRODUCTION .....	13
INPUT SAMPLING .....	13
RESET LEVEL CLAMPING (RLC).....	13
CDS/NON-CDS PROCESSING .....	16
OFFSET ADJUST AND PROGRAMMABLE GAIN .....	16
ADC INPUT BLACK LEVEL ADJUST .....	17
OVERALL SIGNAL FLOW SUMMARY.....	18
CALCULATING THE OUTPUT CODE FOR A GIVEN INPUT .....	19
REFERENCES .....	20
POWER MANAGEMENT .....	20
CONTROL INTERFACE.....	20
NORMAL OPERATING MODES .....	21
<b>DEVICE CONFIGURATION</b> .....	<b>22</b>
REGISTER MAP .....	22
REGISTER MAP DESCRIPTION .....	23
<b>APPLICATIONS INFORMATION</b> .....	<b>26</b>
RECOMMENDED EXTERNAL COMPONENTS .....	26
RECOMMENDED EXTERNAL COMPONENT VALUES .....	26
<b>PACKAGE DIMENSIONS</b> .....	<b>27</b>
<b>IMPORTANT NOTICE</b> .....	<b>28</b>
ADDRESS: .....	28

**PIN CONFIGURATION**



**ORDERING INFORMATION**

DEVICE	TEMPERATURE RANGE	PACKAGE	MOISTURE SENSITIVITY LEVEL	PEAK SOLDERING TEMPERATURE
WM8216SEFL	0 to 70°C	32-lead QFN (5x5x0.9mm) (Pb free)	MSL1	260°C
WM8216SEFL/R	0 to 70°C	32-lead QFN (5x5x0.9mm) (Pb free, tape and reel)	MSL1	260°C

**Note:**

Reel quantity = 3,500

## PIN DESCRIPTION

PIN	NAME	TYPE	DESCRIPTION
1	RSMP	Digital input	Reset sample pulse (when CDS=1) or clamp control (CDS=0)
2	MCLK	Digital input	Master (ADC) clock. This clock determines the ADC conversion rate.
3	DGND	Supply	Digital ground.
4	SEN	Digital input	Enables the serial interface when high.
5	DVDD2	Supply	Digital supply, all digital I/O pins.
6	SDI	Digital input	Serial data input.
7	SCK	Digital input	Serial clock.
8	NC	No connect	No internal connection.
9	NC	No connect	No internal connection.
			Digital output data bus. ADC output data (d9:d0) is available in 10-bit parallel format.
10	OP[0]	Digital output	d0 (LSB)
11	OP[1]	Digital output	d1
12	OP[2]	Digital output	d2
13	OP[3]	Digital output	d3
14	OP[4]	Digital output	d4
15	OP[5]	Digital output	d5
16	OP[6]	Digital output	d6
17	OP[7]	Digital output	d7
18	OP[8]	Digital output	d8
19	OP[9]/SDO	Digital output	d9 (MSB)
			Alternatively, pin OP[9]/SDO may be used to output register read-back data when OEB=0, OPD(register bit)=0 and SEN has been pulsed high. See Serial Interface description in Device Description section for further details.
20	AVDD	Supply	Analogue supply. This must be operated at the same potential as DVDD1.
21	AGND1	Supply	Analogue ground.
22	VRB	Analogue output	Lower reference voltage. This pin must be connected to AGND via a decoupling capacitor.
23	VRT	Analogue output	Upper reference voltage. This pin must be connected to AGND via a decoupling capacitor.
24	VRX	Analogue output	Input return bias voltage. This pin must be connected to AGND via a decoupling capacitor.
25	VRLC/VBIAS	Analogue I/O	Selectable analogue output voltage for RLC or single-ended bias reference. This pin would typically be connected to AGND via a decoupling capacitor. VRLC can be externally driven if programmed Hi-Z.
26	TEST	Analogue I/O	Used for test purposes only. Do not externally connect – leave this pin floating.
27	EINP	Analogue input	Even channel input video.
28	OINP	Analogue input	Odd channel input video.
29	AGND2	Supply	Analogue ground.
30	DVDD1	Supply	Digital supply for logic and clock generator. This must be operated at the same potential as AVDD.
31	OEB	Digital input	Output Hi-Z control. All digital outputs set to high-impedance state when input pin OEB=1 or register bit OPD=1.
32	VSMP	Digital input	Video sample pulse.

## ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings are stress ratings only. Permanent damage to the device may be caused by continuously operating at or beyond these limits. Device functional operating limits and guaranteed performance specifications are given under Electrical Characteristics at the test conditions specified.



ESD Sensitive Device. This device is manufactured on a CMOS process. It is therefore generically susceptible to damage from excessive static voltages. Proper ESD precautions must be taken during handling and storage of this device.

Wolfson tests its package types according to IPC/JEDEC J-STD-020B for Moisture Sensitivity to determine acceptable storage conditions prior to surface mount assembly. These levels are:

MSL1 = unlimited floor life at <30°C / 85% Relative Humidity. Not normally stored in moisture barrier bag.

MSL2 = out of bag storage for 1 year at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.

MSL3 = out of bag storage for 168 hours at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.

The Moisture Sensitivity Level for each package type is specified in Ordering Information.

CONDITION	MIN	MAX
Analogue supply voltage: AVDD	GND - 0.3V	GND + 4.2V
Digital supply voltages: DVDD1 – 2	GND - 0.3V	GND + 4.2V
Digital ground: DGND	GND - 0.3V	GND + 0.3V
Analogue grounds: AGND1 – 2	GND - 0.3V	GND + 0.3V
Digital inputs, digital outputs and digital I/O pins	GND - 0.3V	DVDD2 + 0.3V
Analogue inputs (EINP, OINP)	GND - 0.3V	AVDD + 0.3V
Other pins	GND - 0.3V	AVDD + 0.3V
Operating temperature range: T <sub>A</sub>	0°C	+70°C
Storage temperature prior to soldering	30°C max / 85% RH max	
Storage temperature after soldering	-65°C	+150°C

### Notes:

- GND denotes the voltage of any ground pin.
- AGND1, AGND2 and DGND pins are intended to be operated at the same potential. Differential voltages between these pins will degrade performance.

## RECOMMENDED OPERATING CONDITIONS

CONDITION	SYMBOL	MIN	TYP	MAX	UNITS
Operating temperature range	T <sub>A</sub>	0		70	°C
Analogue supply voltage	AVDD	2.97	3.3	3.63	V
Digital core supply voltage	DVDD1	2.97	3.3	3.63	V
Digital I/O supply voltage	DVDD2	2.97	3.3	3.63	V

### Notes:

- DVDD2 should be operated at the same potential as DVDD1 ± 0.3V.

## THERMAL PERFORMANCE

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Performance</b>						
Thermal resistance – junction to case	R <sub>θJC</sub>	T <sub>ambient</sub> = 25°C		10.27		°C/W
Thermal resistance – junction to ambient	R <sub>θJA</sub>			29.45		°C/W

### Notes:

- Figures given are for package mounted on 4-layer FR4 according to JESD51-5 and JESD51-7.

## ELECTRICAL CHARACTERISTICS

## Test Conditions

AVDD = DVDD1 = DVDD2 = 3.3V, AGND = DGND = 0V, T<sub>A</sub> = 25°C, MCLK = 60MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Overall System Specification (including 10-bit ADC, PGA, Offset and CDS functions)</b>						
Conversion rate				60		MSPS
Full-scale input voltage range (see Note 1)		LOWREFS=0, Max Gain		0.25		Vp-p
		LOWREFS=0, Min Gain		3.03		Vp-p
		LOWREFS=1, Max Gain		0.15		Vp-p
		LOWREFS=1, Min Gain		1.82		Vp-p
Input signal limits (see Note 2)	V <sub>IN</sub>		AGND-0.3		AVDD+0.3	V
Input capacitance				10		pF
Input switching impedance				45		Ω
Full-scale transition error		Gain = 0dB; PGA[7:0] = 4B(hex)		20		mV
Zero-scale transition error		Gain = 0dB; PGA[7:0] = 4B(hex)		20		mV
Differential non-linearity	DNL			0.75		LSB
Integral non-linearity	INL			2		LSB
Channel to channel gain matching				1%		%
Output noise		Min Gain		0.2		LSB rms
		Max Gain		2.15		LSB rms
<b>References</b>						
Upper reference voltage	VRT	LOWREFS=0	1.95	2.05	2.25	V
		LOWREFS=1		1.85		V
Lower reference voltage	VRB	LOWREFS=0	0.95	1.05	1.25	V
		LOWREFS=1		1.25		V
Input return bias voltage	VRX			1.25		V
Diff. reference voltage (VRT-VRB)	V <sub>RTB</sub>	LOWREFS=0	0.9	1.0	1.10	V
		LOWREFS=1		0.6		V
Output resistance VRT, VRB, VRX				1		Ω
<b>VRLC/Reset-Level Clamp (RLC)</b>						
RLC switching impedance				45		Ω
VRLC short-circuit current				2		mA
VRLC output resistance				2		Ω
VRLC Hi-Z leakage current		VRLC = 0 to AVDD			1	μA
RLCDAC resolution				4		bits
RLCDAC step size, RLCDAC = 0	V <sub>RLCSTEP</sub>	AVDD=3.3V		0.173		V/step
RLCDAC step size, RLCDAC = 1	V <sub>RLCSTEP</sub>	LOWREFS = 0		0.11		V/step
RLCDAC output voltage at code 0(hex), RLCDACRNG = 0	V <sub>RLCBOT</sub>	AVDD=3.3V		0.4		V
RLCDAC output voltage at code 0(hex), RLCDACRNG = 1	V <sub>RLCBOT</sub>	LOWREFS = 0		0.4		V
RLCDAC output voltage at code F(hex) RLCDACRNG, = 0	V <sub>RLCTOP</sub>	AVDD=3.3V		3.0		V
RLCDAC output voltage at code F(hex), RLCDACRNG = 1	V <sub>RLCTOP</sub>	LOWREFS = 0		2.05		V
RLCDAC	DNL		-0.5		+0.5	LSB
RLCDAC	INL			+/-0.5		LSB

## Notes:

1. **Full-scale input voltage** denotes the peak input signal amplitude that can be gained to match the ADC full-scale input range.
2. **Input signal limits** are the limits within which the full-scale input voltage signal must lie.

**Test Conditions**AVDD = DVDD1 = DVDD2 = 3.3V, AGND = DGND = 0V, T<sub>A</sub> = 25°C, MCLK = 60MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Offset DAC, Monotonicity Guaranteed</b>						
Resolution				8		bits
Differential non-linearity	DNL			0.15		LSB
Integral non-linearity	INL			0.4		LSB
Step size				2.04		mV/step
Output voltage		Code 00(hex) Code FF(hex)		-255 +255		mV mV
<b>Programmable Gain Amplifier</b>						
Resolution				9		bits
Gain				$0.66 + \frac{7.34}{511} * PGA[8:0]$		V/V
Max gain, each channel	G <sub>MAX</sub>			8		V/V
Min gain, each channel	G <sub>MIN</sub>			0.66		V/V
Channel matching				1		%
<b>Analogue to Digital Converter</b>						
Resolution				10		bits
Speed					60	MSPS
Full-scale input range (2*(VRT-VRB))		LOWREFS=0		2		V
		LOWREFS=1		1.2		V
<b>DIGITAL SPECIFICATIONS</b>						
<b>Digital Inputs</b>						
High level input voltage	V <sub>IH</sub>		0.7 * DVDD2			V
Low level input voltage	V <sub>IL</sub>				0.2 * DVDD2	V
High level input current	I <sub>IH</sub>				1	µA
Low level input current	I <sub>IL</sub>				1	µA
Input capacitance	C <sub>I</sub>			5		pF
<b>Digital Outputs</b>						
High level output voltage	V <sub>OH</sub>	I <sub>OH</sub> = 1mA	DVDD2 - 0.5			V
Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> = 1mA			0.5	V
High impedance output current	I <sub>OZ</sub>				1	µA
<b>Digital IO Pins</b>						
Applied high level input voltage	V <sub>IH</sub>		0.7 * DVDD2			V
Applied low level input voltage	V <sub>IL</sub>				0.2 * DVDD2	V
High level output voltage	V <sub>OH</sub>	I <sub>OH</sub> = 1mA	DVDD2 - 0.5			V
Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> = 1mA			0.5	V
Low level input current	I <sub>IL</sub>				1	µA
High level input current	I <sub>IH</sub>				1	µA
Input capacitance	C <sub>I</sub>			5		pF
High impedance output current	I <sub>OZ</sub>				1	µA
<b>Supply Currents</b>						
Total supply current – active				118		mA
Analogue supply current – active (two channel mode)				105		mA
Digital supply current, – active (two channel mode)				13		mA
Supply current – full power down mode				20		µA

## INPUT VIDEO SAMPLING

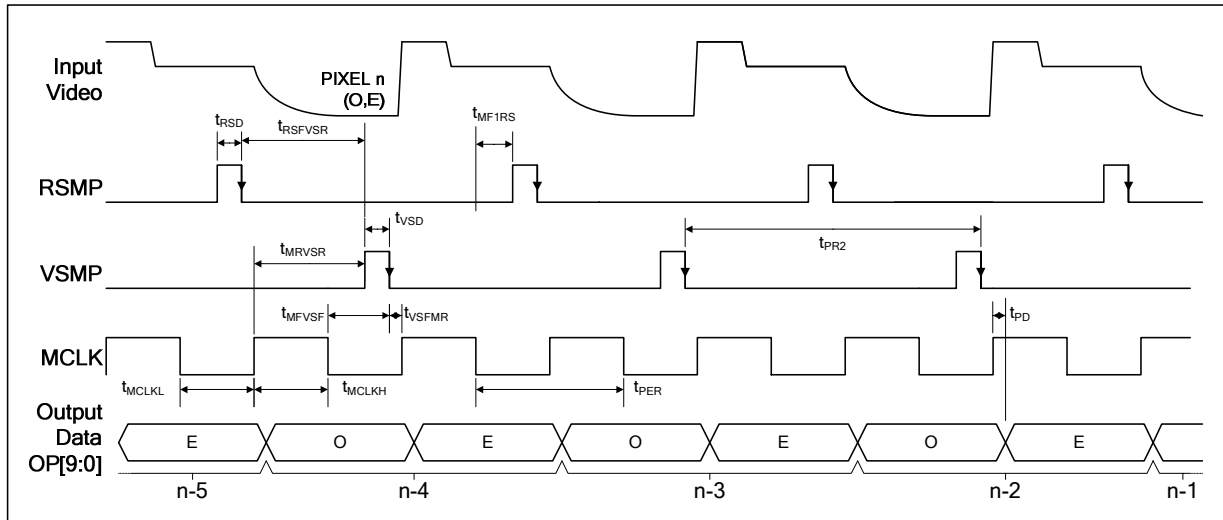


Figure 1 Two-channel CDS Operation (CDS=1)

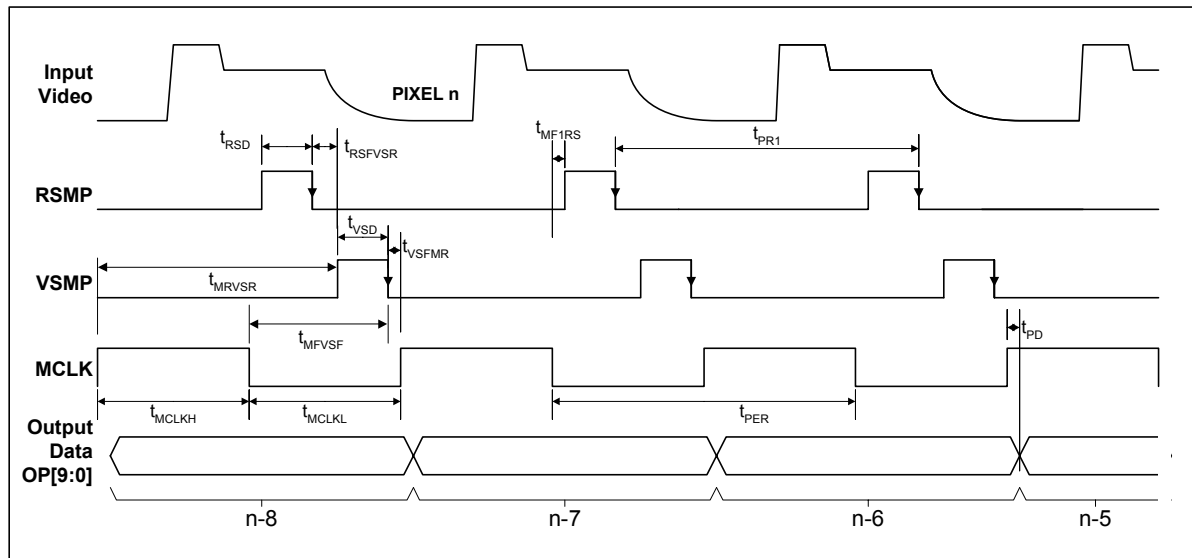


Figure 2 One-channel CDS Operation (CDS=1)

## Notes:

1. The relationship between input video signal and sample points is controlled by VSMP and RSMP.
2. When VSMP is high the input video signal is connected to the Video sampling capacitors.
3. When RSMP is high the input video signal is connected to the Reset sampling capacitors.
4. RSMP must not go high before the first falling edge of MCLK after VSMP goes low.
5. It is required that the falling edge of VSMP should occur before the rising edge of MCLK.
6. In 1-channel CDS mode it is not possible to have equally spaced Video and Reset sample points with a 45MHz MCLK.
7. Non-CDS operation is also possible; RSMP is not required in this mode but can be used to control input clamping.

**Test Conditions**

AVDD = DVDD1 = DVDD2 = 3.3V, AGND = DGND = 0V, T<sub>A</sub> = 25°C, MCLK = 60MHz for 2-channel mode and 45MHz for 1-channel mode unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
MCLK period – 2 channel mode 1 channel mode	t <sub>PER</sub>		16.6 22.2			ns
MCLK high period – 2 channel mode 1 channel mode	t <sub>MCLKH</sub>		7.5	8.3 11.1		ns
MCLK low period – 2 channel mode 1 channel mode	t <sub>MCLKL</sub>		7.5	8.3 11.1		ns
RSMP pulse high time	t <sub>RS</sub>		5			ns
VSMP pulse high time	t <sub>VS</sub>		5			ns
RSMP falling to VSMP rising time	t <sub>RSFVSR</sub>		0			ns
MCLK rising to VSMP rising time	t <sub>MRVSR</sub>		3			ns
MCLK falling to VSMP falling time	t <sub>MFVSF</sub>		5			ns
VSMP falling to MCLK rising time <sup>2</sup>	t <sub>VSFMR</sub>		1			ns
1 <sup>st</sup> MCLK falling edge after VSMP falling to RSMP rising time	t <sub>MF1RS</sub>		1			ns
2-channel mode pixel rate	t <sub>PR2</sub>		33.2			ns
1-channel mode pixel rate	t <sub>PR1</sub>		16.6			ns
Output propagation delay	t <sub>PD</sub>			5	10	ns
Output latency. From 1 <sup>st</sup> rising edge of MCLK after VSMP falling to data output	LAT			7		MCLK periods

**Notes:**

- Parameters are measured at 50% of the rising/falling edge.
- In 1-Channel mode, if the VSMP falling edge is placed more than 3ns before the rising edge of MCLK the output amplitude of the WM8216 will decrease.

**SERIAL INTERFACE**

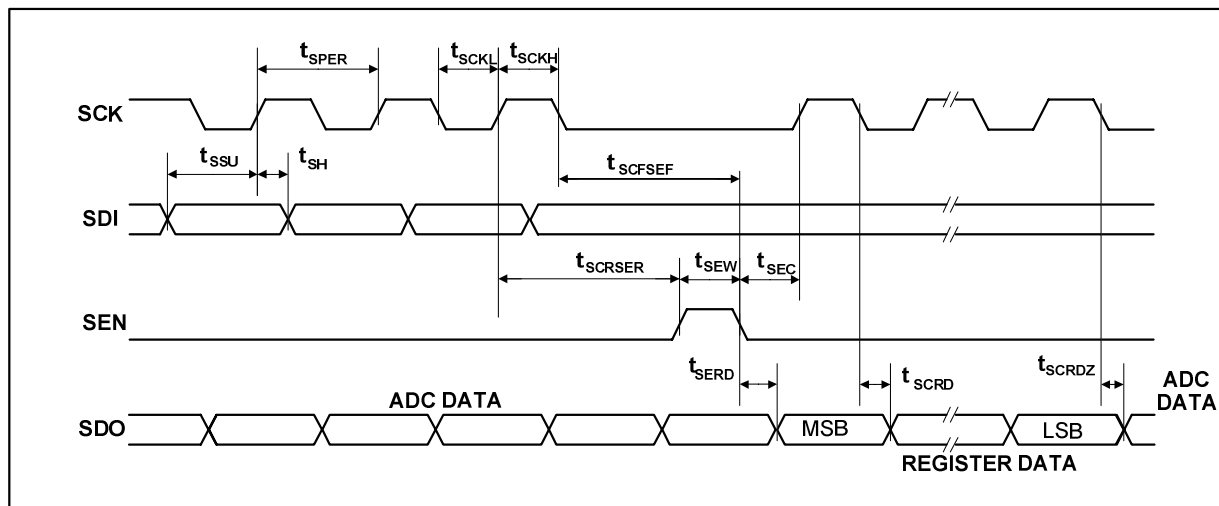


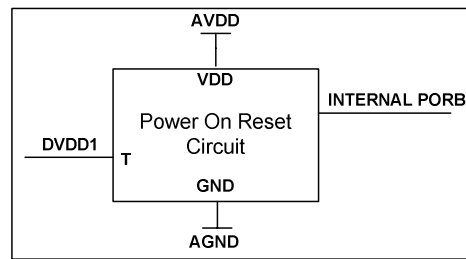
Figure 3 Serial Interface Timing

**Test Conditions**AVDD = DVDD1 = DVDD2 = 3.3V, AGND = DGND = 0V, T<sub>A</sub> = 25°C unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
SCK period	t <sub>SPER</sub>		83.3			ns
SCK high	t <sub>SCKH</sub>		37.5			ns
SCK low	t <sub>SCKL</sub>		37.5			ns
SDI set-up time	t <sub>SSU</sub>		6			ns
SDI hold time	t <sub>SH</sub>		6			ns
SCK Rising to SEN Rising	t <sub>SCRSEF</sub>		37.5			ns
SCK Falling to SEN Falling	t <sub>SCFSEF</sub>		12			ns
SEN to SCK set-up time	t <sub>SEC</sub>		12			ns
SEN pulse width	t <sub>SEW</sub>		60			ns
SEN low to SDO = Register data	t <sub>SERD</sub>				30	ns
SCK low to SDO = Register data	t <sub>SCRD</sub>				30	ns
SCK low to SDO = ADC data	t <sub>SCRDZ</sub>				30	ns

**Note:** 1. Parameters are measured at 50% of the rising/falling edge

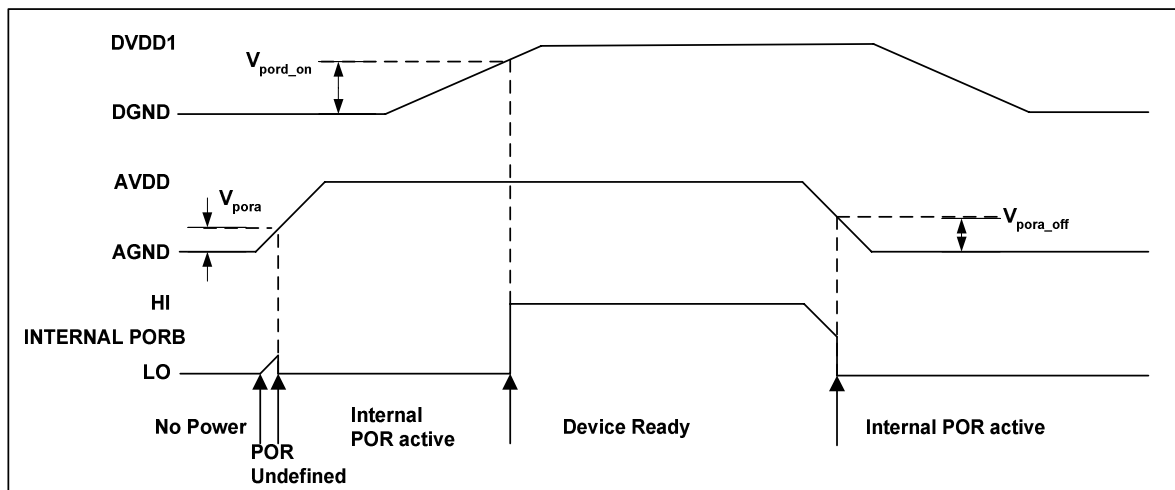
## INTERNAL POWER ON RESET CIRCUIT



**Figure 4 Internal Power On Reset Circuit Schematic**

The WM8216 includes an internal Power-On-Reset Circuit, as shown in Figure 4, which is used to reset the digital logic into a default state after power up. The POR circuit is powered from AVDD and monitors DVDD1. It asserts PORB low if AVDD or DVDD1 is below a minimum threshold.

The power supplies can be brought up in any order but it is important that either AVDD is brought up before DVDD or vice versa as shown in Figure 5 and Figure 6.

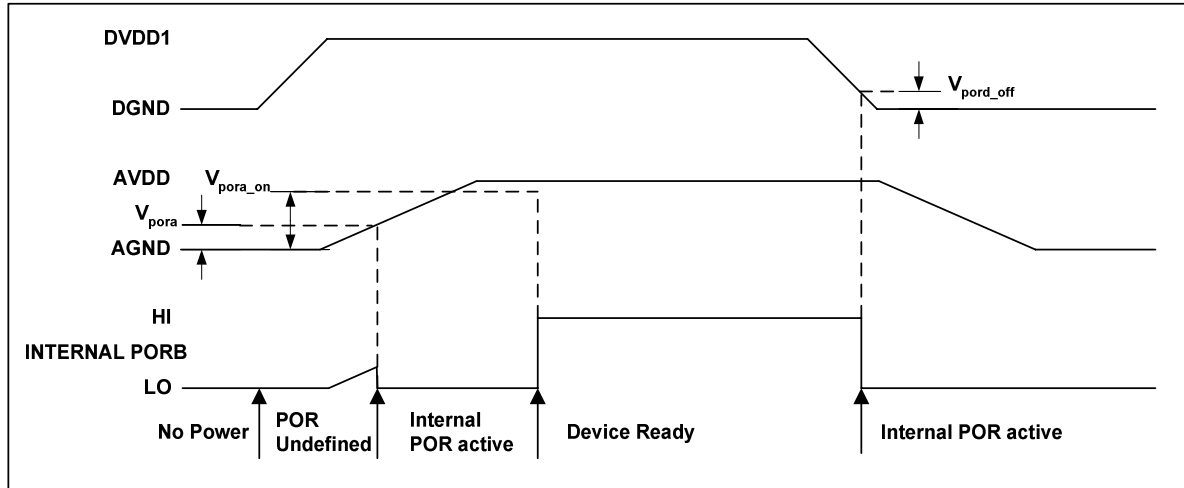


**Figure 5 Typical Power up Sequence where AVDD is Powered before DVDD1**

Figure 5 shows a typical power-up sequence where AVDD comes up first. When AVDD goes above the minimum threshold,  $V_{pora}$ , there is enough voltage for the circuit to guarantee PORB is asserted low and the chip is held in reset. In this condition, all writes to the control interface are ignored. Now AVDD is at full supply level. Next DVDD1 rises to  $V_{pord\_on}$  and PORB is released high and all registers are in their default state and writes to the control interface may take place.

**Note:** It is recommended that every time power is cycled to the WM8216 a software reset is written to the software register to ensure that the contents of the control registers are at their default values before carrying out any other register writes.

On power down, where AVDD falls first, PORB is asserted low whenever AVDD drops below the minimum threshold  $V_{pora\_off}$ .



**Figure 6 Typical Power up Sequence where DVDD1 is Powered before AVDD**

Figure 6 shows a typical power-up sequence where DVDD1 comes up first. First it is assumed that DVDD1 is already up to specified operating voltage. When AVDD goes above the minimum threshold,  $V_{pora}$ , there is enough voltage for the circuit to guarantee PORB is asserted low and the chip is held in reset. In this condition, all writes to the control interface are ignored. When AVDD rises to  $V_{pora\_on}$ , PORB is released high and all registers are in their default state and writes to the control interface may take place.

On power down, where DVDD1 falls first, PORB is asserted low whenever DVDD1 drops below the minimum threshold  $V_{pord\_off}$ .

SYMBOL	TYP	UNIT
$V_{pora}$	0.6	V
$V_{pora\_on}$	1.2	V
$V_{pora\_off}$	0.6	V
$V_{pord\_on}$	0.7	V
$V_{pord\_off}$	0.6	V

**Table 1 Typical POR Operation (typical values, not tested)**

## DEVICE DESCRIPTION

### INTRODUCTION

A block diagram of the device showing the signal path is presented on the front page of this datasheet.

The WM8216 samples up to two inputs (OINP and EINP) simultaneously. The device then processes the sampled video signal with respect to the video reset level or an internally/externally generated reference level using either one or two processing channels.

Each processing channel consists of an Input Sampling block with optional Reset Level Clamping (RLC) and Correlated Double Sampling (CDS), an 8-bit programmable offset DAC and a 9-bit Programmable Gain Amplifier (PGA).

The ADC then converts each resulting analogue signal to a 10-bit digital word. The digital output from the ADC is presented in parallel on the 10-bit wide output bus, OP[9:0]. The ten output pins can be set to a high impedance state using either the OEB control pin or the OPD register bit.

On-chip control registers determine the configuration of the device, including the offsets and gains applied to each channel. These registers are programmable via a serial interface.

### INPUT SAMPLING

The WM8216 can sample and process up to two inputs through one or two processing channels as follows:

**Two Channel Pixel-by-pixel:** Two input channels (OINP and EINP) are simultaneously sampled for each pixel and a separate channel processes each input. The signals are then multiplexed into the ADC, which converts both inputs within the pixel period.

**Monochrome:** A single chosen input (OINP or EINP) is sampled, processed by the corresponding channel, and converted by the ADC. The choice of input and channel can be changed via the control interface. The unused channel is powered down when this mode is selected.

### RESET LEVEL CLAMPING (RLC)

To ensure that the signal applied to the WM8216 lies within the supply voltage range (0V to AVDD) the output signal from a CCD is usually level shifted by coupling through a capacitor,  $C_{IN}$ . The RLC circuit clamps the WM8216 side of this capacitor to a suitable voltage through a CMOS switch during the CCD reset period (pixel clamping) or during the black pixels (line clamping). In order for clamping to produce correct results the input voltage during the clamping must be a constant value.

The WM8216 allows the user to control the RLC switch in a variety of ways. Odd and Even channels are identical, each with its own clamp switch controlled by the common CLMP signal.

The method of control chosen depends upon the characteristics of the input video. The RLCEN register bit must be set to 1 to enable clamping, otherwise the RLC switch cannot be closed (by default RLCEN=1).

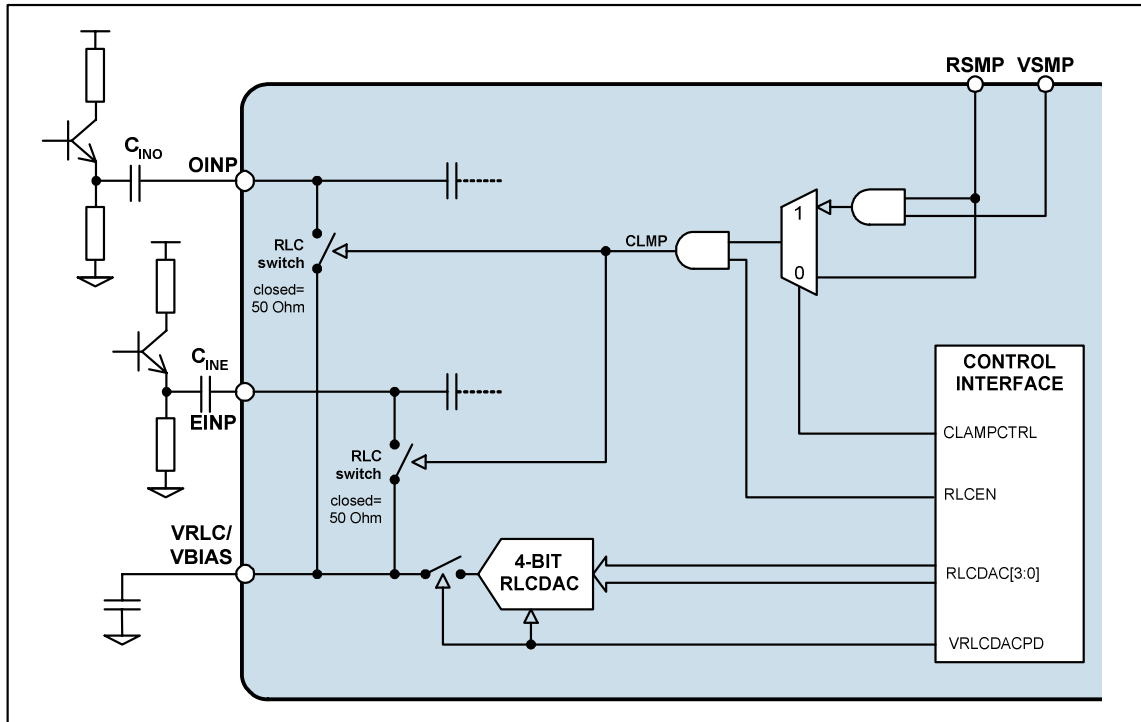


Figure 7 RLC Clamp Control Options

When an input waveform has a stable reference level on every pixel it may be desirable to clamp every pixel during this period. Setting CLMPCTRL=0 means that the RLC switch is closed whenever the RSMP input pin is high, as shown in Figure 8.

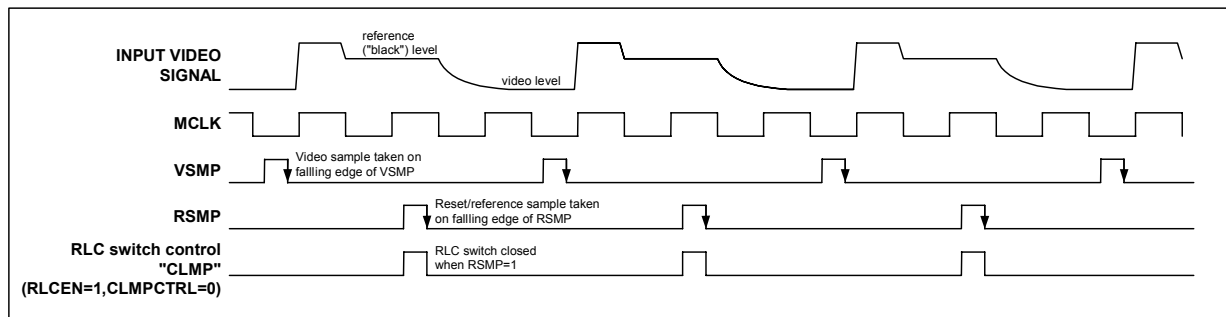


Figure 8 Reset Level Clamp Operation (CLMPCTRL=0), CDS operation shown, non-CDS also possible

In situations where the input video signal does not have a stable reference level it may be necessary to clamp only during those pixels which have a known state (e.g. the dummy, or "black" pixels at the start or end of a line on most image sensors). This is known as line-clamping and relies on the input capacitor to hold the DC level between clamp intervals. However, it should be noted that in non-CDS mode, this method of operation will result in a slow drift in the output codes. In non-CDS mode (CDS=0) line clamping can be done directly by controlling the RSMP input pin to go high during the black pixels only.

Alternatively it is possible to use RSMP to identify the black pixels and enable the clamp at the same time as the input is being sampled (i.e. when VSMP is high and RSMP is high). This mode is enabled by setting CLMPCTRL=1 and the operation is shown in Figure 9.

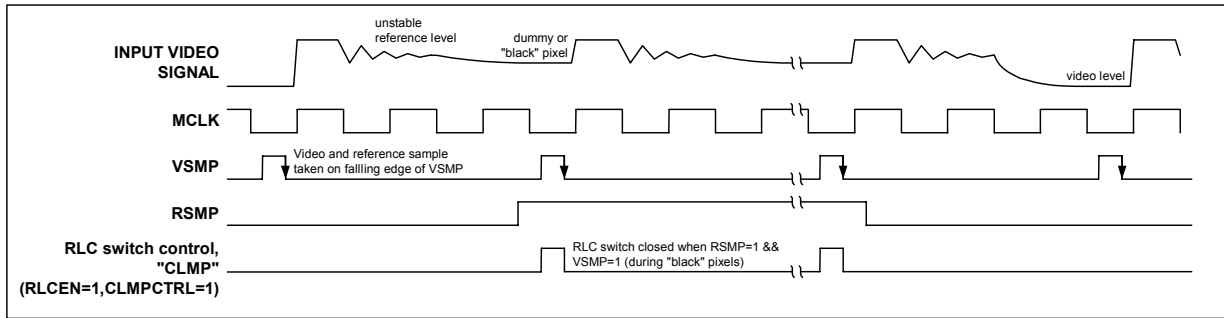


Figure 9 Reset Level Clamp Operation (CLMPCTRL=1), non-CDS mode only

RLCEN	CLAMPCTRL	OUTCOME	USE
0	X	RLC is not enabled. RLC switch is always open.	When input is DC coupled and within supply rails.
1	0	RLC switch is controlled directly from RSMP input pin: RSMP=0: switch is open RSMP=1: switch is closed	When user explicitly provides a reset sample signal and the input video waveform has a suitable reset level.
1	1	VSMP applied as normal, RSMP is used to indicate the location of black pixels RLC switch is controlled by logical combination of RSMP and VSMP: RSMP && VSMP = 0: switch is open RSMP && VSMP = 1: switch is closed	When clamping during the video period of black pixels or there is no stable per-pixel reference level.

Table 2 Reset Level Clamp Control Summary

## CDS/NON-CDS PROCESSING

For CCD type input signals, containing a fixed reference/reset level, the signal may be processed using Correlated Double Sampling (CDS), which will remove pixel-by-pixel common mode noise. With CDS processing the input waveform is sampled at two different points in time for each pixel, once during the reference/reset level and once during the video level. To sample using CDS, register bit CDS must be set to 1 (default). This causes the signal reference to come from the video reference level as shown in Figure 10.

The video sample is always taken on the falling edge of the input VSMP signal (VS). In CDS-mode the reset level is sampled on the falling edge of the RSMP input signal (RS).

For input signals that do not contain a reference/reset level (e.g. CIS sensor signals), non-CDS processing is used (CDS=0). In this case, the video level is processed with respect to the voltage on pin VRLC/VBIAS. The VRLC/VBIAS voltage is sampled at the same time as VSMP samples the video level in this mode.

It should be noted that if a coupling capacitor is used on OINP or EINP in non-CDS mode, a drift in output code will be seen, unless the input is clamped each pixel – see Reset Level Clamping section. The drift effect can be reduced by increasing the size of coupling capacitor used or reducing the number of samples between clamping.

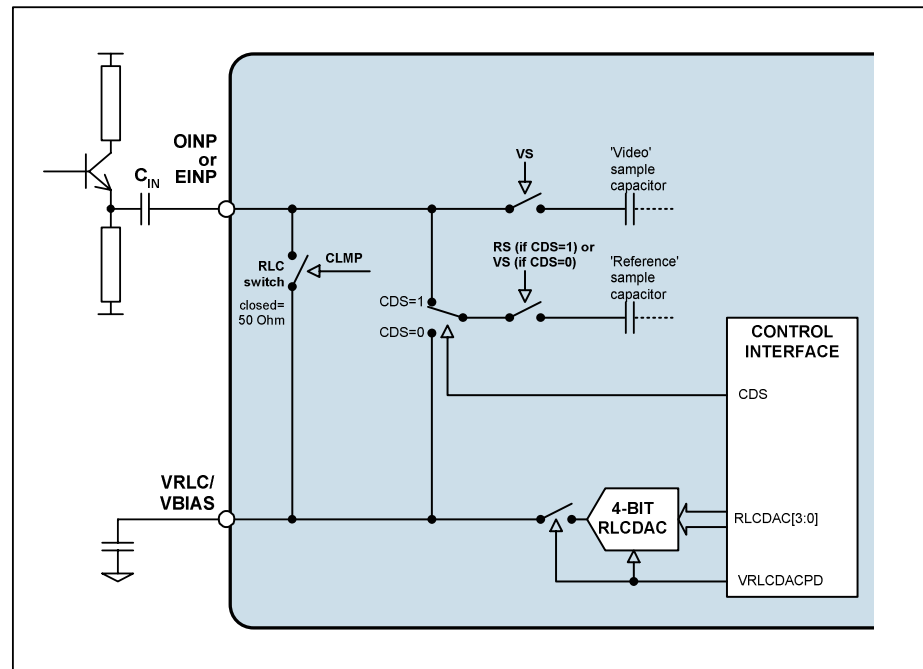


Figure 10 CDS/non-CDS Input Configuration

## OFFSET ADJUST AND PROGRAMMABLE GAIN

The output from the CDS block is a differential signal, which is added to the output of an 8-bit Offset DAC to compensate for offsets and then amplified by a 9-bit PGA. The gain and offset for each channel are independently programmable by writing to control bits DAC[7:0] and PGA[8:0].

The gain characteristic of the WM8216 PGA is shown in Figure 11.. Figure 12 shows the maximum device input voltage that can be gained up to match the ADC full-scale input range (default=2V).

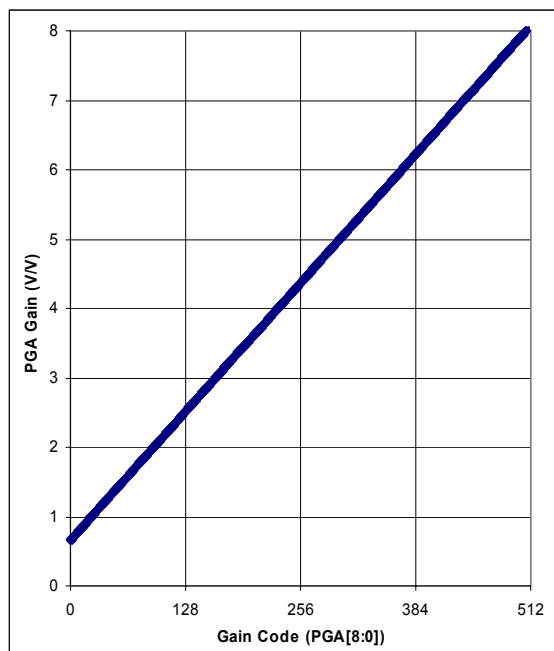


Figure 11 PGA Gain Characteristic

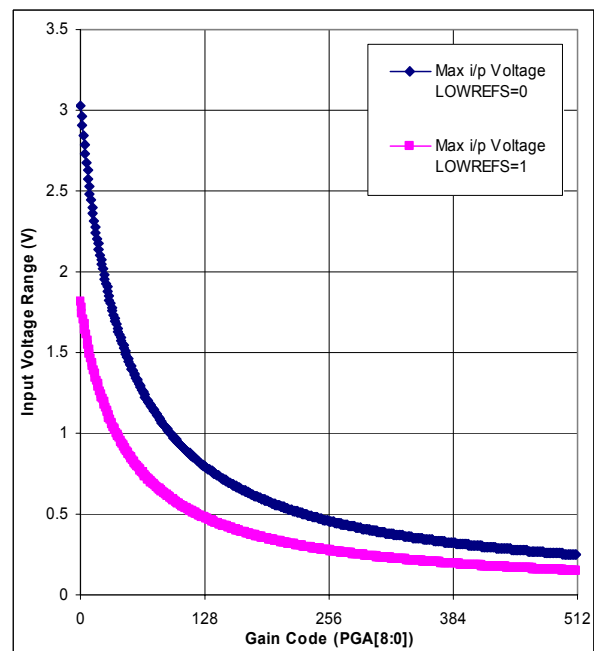


Figure 12 Peak Input Voltage to Match ADC Full-scale Range

## ADC INPUT BLACK LEVEL ADJUST

The output from the PGA can be offset to match the full-scale range of the differential ADC ( $2 \times [VRT-VRB]$ ).

For negative-going input video signals, a black level (zero differential) output from the PGA should be offset to the top of the ADC range by setting register bits PGAFS[1:0]=10. This will give an output code of 3FF (hex) from the WM8216 for zero input. If code zero is required for zero differential input then the INVOP bit should be set.

For positive going input signals the black level should be offset to the bottom of the ADC range by setting PGAFS[1:0]=11. This will give an output code of 000 (hex) from the WM8216 for zero input.

Bipolar input video is accommodated by setting PGAFS[1:0]=00 or PGAFS[1:0]=01. Zero differential input voltage gives mid-range ADC output, 1FF (hex).

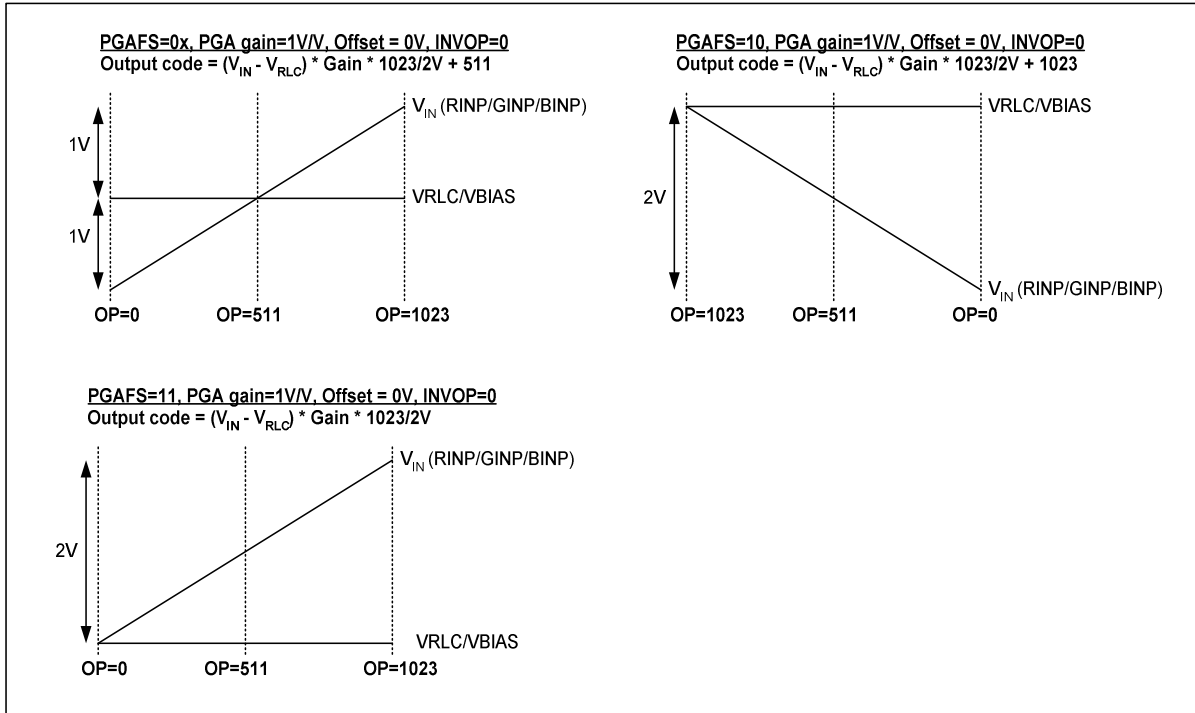


Figure 13 ADC Input Black Level Adjust Settings

OVERALL SIGNAL FLOW SUMMARY

Figure 14 represents the processing of the video signal through the WM8216.

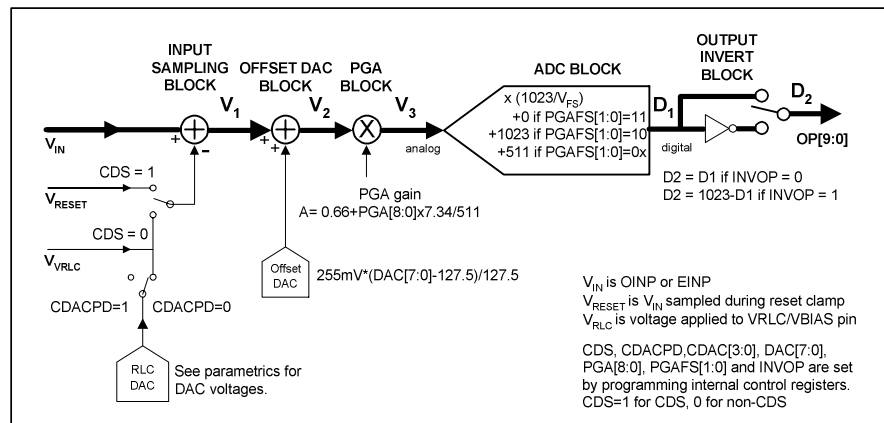


Figure 14 Overall Signal Flow

The **INPUT SAMPLING BLOCK** produces an effective input voltage  $V_1$ . For CDS, this is the difference between the input video level  $V_{IN}$  and the input reset level  $V_{RESET}$ . For non-CDS this is the difference between the input video level  $V_{IN}$  and the voltage on the VRLC/VBIAS pin,  $V_{RLC}$ , optionally set via the RLC DAC.

The **OFFSET DAC BLOCK** then adds the amount of fine offset adjustment required to move the black level of the input signal towards 0V, producing  $V_2$ .

The **PGA BLOCK** then amplifies the white level of the input signal to maximise the ADC range, outputting voltage  $V_3$ .

The **ADC BLOCK** then converts the analogue signal,  $V_3$ , to a 10-bit unsigned digital output,  $D_1$ .

The digital output is then inverted, if required, through the **OUTPUT INVERT BLOCK** to produce  $D_2$ .

## CALCULATING THE OUTPUT CODE FOR A GIVEN INPUT

The following equations describe the processing of the video and reset level signals through the WM8216.

### INPUT SAMPLING BLOCK: INPUT SAMPLING AND REFERENCING

If CDS = 1, (i.e. CDS operation) the previously sampled reset level,  $V_{\text{RESET}}$ , is subtracted from the input video.

$$V_1 = V_{\text{IN}} - V_{\text{RESET}} \quad \text{Eqn. 1}$$

If CDS = 0, (non-CDS operation) the simultaneously sampled voltage on pin VRLC is subtracted instead.

$$V_1 = V_{\text{IN}} - V_{\text{VRLC}} \quad \text{Eqn. 2}$$

If VRLCDACPD = 1,  $V_{\text{VRLC}}$  is an externally applied voltage on pin VRLC/VBIAS.

If VRLCDACPD = 0,  $V_{\text{VRLC}}$  is the output from the internal RLC DAC.

$$V_{\text{VRLC}} = (V_{\text{RLCSTEP}} * \text{RLC DAC}[3:0]) + V_{\text{RLCBOT}} \quad \text{Eqn. 3}$$

$V_{\text{RLCSTEP}}$  is the step size of the RLC DAC and  $V_{\text{RLCBOT}}$  is the minimum output of the RLC DAC.

### OFFSET DAC BLOCK: OFFSET (BLACK-LEVEL) ADJUST

The resultant signal  $V_1$  is added to the Offset DAC output.

$$V_2 = V_1 + \{255\text{mV} * (\text{DAC}[7:0] - 127.5)\} / 127.5 \quad \text{Eqn. 4}$$

### PGA NODE: GAIN ADJUST

The signal is then multiplied by the PGA gain.

$$V_3 = V_2 * (0.66 + \text{PGA}[8:0] * 7.34 / 511) \quad \text{Eqn. 5}$$

### ADC BLOCK: ANALOGUE-DIGITAL CONVERSION

The analogue signal is then converted to a 10-bit unsigned number, with input range configured by PGAFS[1:0].

$$D_1[9:0] = \text{INT}\{ (V_3 / V_{\text{FS}}) * 1023\} + 511 \quad \text{PGAFS}[1:0] = 00 \text{ or } 01 \quad \text{Eqn. 6}$$

$$D_1[9:0] = \text{INT}\{ (V_3 / V_{\text{FS}}) * 1023\} \quad \text{PGAFS}[1:0] = 11 \quad \text{Eqn. 7}$$

$$D_1[9:0] = \text{INT}\{ (V_3 / V_{\text{FS}}) * 1023\} + 1023 \quad \text{PGAFS}[1:0] = 10 \quad \text{Eqn. 8}$$

where the ADC full-scale range,  $V_{\text{FS}} = 2\text{V}$  when LOWREFS=0 and  $V_{\text{FS}} = 1.2\text{V}$  when LOWREFS=1.

### OUTPUT INVERT BLOCK: POLARITY ADJUST

The polarity of the digital output may be inverted by control bit INVOP.

$$D_2[9:0] = D_1[9:0] \quad (\text{INVOP} = 0) \quad \text{Eqn. 9}$$

$$D_2[9:0] = 1023 - D_1[9:0] \quad (\text{INVOP} = 1) \quad \text{Eqn. 10}$$

## REFERENCES

The ADC reference voltages are derived from an internal band-gap reference, and buffered to pins VRT and VRB, where they must be decoupled to ground. Pin VRX is driven by a similar buffer, and also requires decoupling. The output buffer from the RLCDAC also requires decoupling at pin VRLC/VBIAS.

The ADC references can be switched from the default values (VRT=2.05V, VRB=1.05V, ADC input range=2V) to give a smaller ADC reference range (VRT=1.85V, VRB=1.25V, ADC input range=1.2V) under control of the LOWREFS register bit. Setting LOWREFS=1 allows smaller input signals to be accommodated.

**Note:**

When LOWREFS = 1 the output of the RLCDAC will scale if RLCDACRNG = 1. The max output from RLCDAC will change from 2.05 to 1.85V and the step size will proportionally reduce.

## POWER MANAGEMENT

Power management for the device is performed via the Control Interface. By default the device is fully enabled. The EN bit allows the device to be fully powered down when set low. Individual blocks can be powered down using the bits in Setup Register 5. When in MONO mode the unused input channels are automatically disabled to reduce power consumption.

## CONTROL INTERFACE

The internal control registers are programmable via the serial digital control interface. The register contents can be read back via the serial interface on pin OP[9]/SDO.

It is recommended that a software reset is carried out after the power-up sequence, before writing to any other register. This ensures that all registers are set to their default values (as shown in Table 5).

### SERIAL INTERFACE: REGISTER WRITE

Figure 15 shows register writing in serial mode. Three pins, SCK, SDI and SEN are used. A six-bit address (a5, 0, a3, a2, a1, a0) is clocked in through SDI, MSB first, followed by an eight-bit data word (b7, b6, b5, b4, b3, b2, b1, b0), also MSB first. Setting address bit a4 to 0 indicates that the operation is a register write. Each bit is latched on the rising edge of SCK. When the data has been shifted into the device, a pulse is applied to SEN to transfer the data to the appropriate internal register.

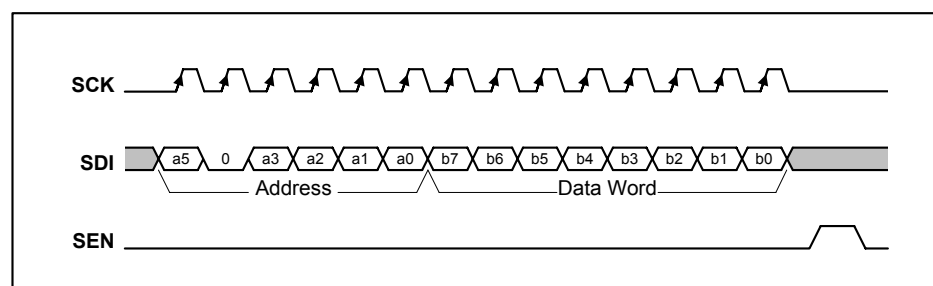


Figure 15 Serial Interface Register Write

A software reset is carried out by writing to Address "000100" with any value of data, (i.e. Data Word = XXXXXXXX).

**SERIAL INTERFACE: REGISTER READ-BACK**

Figure 16 shows register read-back in serial mode. Read-back is initiated by writing to the serial bus as described above but with address bit a4 set to 1, followed by an 8-bit dummy data word. Writing address (a5, 1, a3, a2, a1, a0) will cause the contents (d7, d6, d5, d4, d3, d2, d1, d0) of corresponding register (a5, 0, a3, a2, a1, a0) to be output MSB first on pin SDO (on the falling edge of SCK). Note that pin SDO is shared with an output pin, OP[9], therefore OEB should always be held low and the OPD register bit should be set low when register read-back data is expected on this pin. The next word may be read in to SDI while the previous word is still being output on SDO.

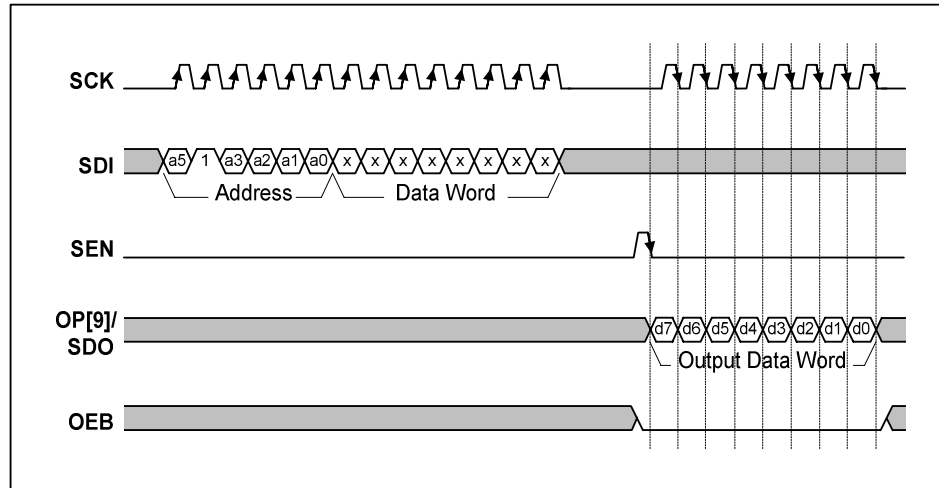


Figure 16 Serial Interface Register Read-back

**NORMAL OPERATING MODES**

Table 3 below shows the normal operating modes of the device. The MCLK speed can be specified along with the MCLK:VSMP ratio to achieve the desired sample rate.

NUMBER OF CHANNELS	DESCRIPTION	CDS AVAILABLE	MAXIMUM SAMPLE RATE	TIMING REQUIREMENTS	CHANNEL MODE SETTINGS
2	Two channel Pixel-by-Pixel	YES	30 MSPS	MCLK max = 60Mhz Minimum MCLK:VSMP ratio = 2:1	MONO = 0 TWOCHAN = 1
1	One channel Pixel-by-Pixel	YES	45 MSPS	MCLK max = 45Mhz Minimum MCLK:VSMP ratio = 1:1	MONO = 1 TWOCHAN = 0

Table 3 WM8216 Normal Operating Modes

**Note:** In one channel mode the WM8216 can operate at 60MHz but DNL/INL values cannot be guaranteed.

Table 4 below shows the different channel mode register settings required to operate the 8216 in 1 and 2 channel modes.

MONO	TWOCHAN	CHAN	MODE DESCRIPTION
0	1	X	2-channel
1	0	0	1-channel mode. Odd Channel
1	0	1	1-channel mode. Even Channel
1	1	X	Invalid mode

Table 4 Sampling Mode Summary

**Note:** Unused input pins should be connected to AGND.

## DEVICE CONFIGURATION

### REGISTER MAP

The following table describes the location of each control bit used to determine the operation of the WM8216.

ADDRESS <a5:a0>	DESCRIPTION	DEF (hex)	RW	BIT							
				b7	b6	b5	b4	b3	b2	b1	b0
000001 (01h)	Setup Reg 1	0B	RW	0	0	PGAFS[1]	PGAFS[0]	TWOCHAN	MONO	CDS	EN
000010 (02h)	Setup Reg 2	20	RW	DEL[1]	DEL[0]	RLCDACRNG	LOWREFS	OPD	INVOP	0	0
000011 (03h)	Setup Reg 3	1F	RW	0	CHAN	CDSREF [1]	CDSREF [0]	RLCDAC[3]	RLCDAC[2]	RLCDAC[1]	RLCDAC[0]
000100 (04h)	Software Reset	00	W								
000110 (06h)	Reserved	00	RW	0	0	0	0	0	0	0	0
000111 (07h)	Setup Reg 5	00	RW	0	VRXPD	ADCREFPD	VRLCDACPD	ADCPD	0	EVENPD	ODDPD
001000 (08h)	Setup Reg 6	20	RW	0	CLAMPCTRL	RLCEN	0	0	0	0	0
001001 (09h)	Reserved	00	RW	0	0	0	0	0	0	0	0
001010 (0Ah)	Reserved	00	RW	0	0	0	0	0	0	0	0
001011 (0Bh)	Reserved	00	RW	0	0	0	0	0	0	0	0
001100 (0Ch)	Reserved	00	RW	0	0	0	0	0	0	0	0
100000 (20h)	DAC Value (Odd)	80	RW	DACO[7]	DACO[6]	DACO[5]	DACO[4]	DACO[3]	DACO[2]	DACO[1]	DACO[0]
100001 (21h)	DAC Value (Even)	80	RW	DACE[7]	DACE[6]	DACE[5]	DACE[4]	DACE[3]	DACE[2]	DACE[1]	DACE[0]
100010 (22h)	Reserved	80	RW	1	0	0	0	0	0	0	0
100011 (23h)	DAC Value (Odd&Even)	80	W	DACOE[7]	DACOE[6]	DACOE[5]	DACOE[4]	DACOE[3]	DACOE[2]	DACOE[1]	DACOE[0]
100100 (24h)	PGA Gain LSB (Odd)	00	RW	0	0	0	0	0	0	0	PGA0[0]
100101 (25h)	PGA Gain LSB (Even)	00	RW	0	0	0	0	0	0	0	PGA0[0]
100110 (26h)	Reserved	00	RW	0	0	0	0	0	0	0	0
100111 (27h)	PGA Gain LSB (Odd&Even)	00	W	0	0	0	0	0	0	0	PGA0E[0]
101000 (28h)	PGA Gain MSBs (Odd)	0C	RW	PGA0[8]	PGA0[7]	PGA0[6]	PGA0[5]	PGA0[4]	PGA0[3]	PGA0[2]	PGA0[1]
101001 (29h)	PGA Gain MSBs (Even)	0C	RW	PGA0E[8]	PGA0E[7]	PGA0E[6]	PGA0E[5]	PGA0E[4]	PGA0E[3]	PGA0E[2]	PGA0E[1]
101010 (2Ah)	Reserved	0C	RW	0	0	0	0	1	1	0	0
101011 (2Bh)	PGA Gain MSBs (Odd&Even)	00	W	PGA0E[8]	PGA0E[7]	PGA0E[6]	PGA0E[5]	PGA0E[4]	PGA0E[3]	PGA0E[2]	PGA0E[1]

**Table 5 Register Map**

## REGISTER MAP DESCRIPTION

The following table describes the function of each of the control bits shown in Table 5.

REGISTER	BIT NO	BIT NAME(S)	DEFAULT (BINARY)	DESCRIPTION
Setup Register 1	0	EN	1	Global Enable 0 = complete power down, 1 = fully active (individual blocks can be disabled using individual powerdown bits – see setup register 5).
	1	CDS	1	Select correlated double sampling mode: 0 = single ended mode, 1 = CDS mode.
	3:2	TWOCHAN / MONO	10	Sampling mode select 10 = Two channel mode 01 = One channel mode. Input channel selected by CHAN register bit (Reg 3 bit 6), unused channel is powered down.
	5:4	PGAFS[1:0]	00	Offsets PGA output to optimise the ADC range for different polarity sensor output signals. Zero differential PGA input signal gives: 0x = Zero output from the PGA (Output code=511) 10 = Full-scale positive output (OP=1023) - use for negative going video. NB, Set INVOP=1 if zero differential input should give a zero output code with negative going video. 11 = Full-scale negative output (OP=0) - use for positive going video
	7:6	Not Used	00	Must be set to 0
Setup Register 2	1:0	Not Used	00	Must be set to 0
	2	INVOP	0	Digitally inverts the polarity of output data. 0 = negative going video gives negative going output, 1 = negative-going video gives positive going output data.
	3	OPD	0	Output Disable. This works with the OEB pin to control the output pins. 0=Digital outputs enabled, 1=Digital outputs high impedance
				OEB (pin)   OPD   OP pins
				0   0   Enabled
				0   1   High Impedance
				1   0   High Impedance
	1   1   High impedance			
	4	LOWREFS	0	Reduces the ADC reference range ( $2 \times [VRT-VRB]$ ), thus changing the max/min input video voltages (ADC ref range/PGA gain). 0= ADC reference range = 2.0V 1= ADC reference range = 1.2V
	5	RLCDACRNG	1	Sets the output range of the RLCDAC. 0 = RLCDAC ranges from 0 to AVDD (approximately), 1 = RLCDAC ranges from 0 to VRT (approximately).
7:6	DEL[1:0]	00	Controls the latency from sample to data appearing on output pins	
			DEL   Latency	
			00   7 MCLK periods	
			01   8 MCLK periods	
			10   9 MCLK periods	
11   10 MCLK periods				

REGISTER	BIT NO	BIT NAME(S)	DEFAULT (BINARY)	DESCRIPTION
Setup Register 3	3:0	RLCDAC[3:0]	1111	Controls RLCDAC driving VRLC/VBIAS pin to define single ended signal reference voltage or Reset Level Clamp voltage. See Electrical Characteristics section for ranges.
	5:4	CDSREF[1:0]	01	CDS mode reset timing adjust. 00 = Advance reset sample by 1 MCLK period (relative to default). 01 = Default reset sample position. 10 = Delay reset sample by 1 MCLK period (relative to default) 11 = Delay reset sample by 2 MCLK periods (relative to default)
	6	CHAN	0	When MONO=0 this register bit has no effect Monochrome mode channel select. 00 = Odd channel select 01 = Even channel select
	7	Not Used	0	Must be set to 0
Software Reset				Any write to Software Reset causes all register bits to be reset. It is recommended that a software reset be performed after a power-up before any other register writes.
Setup Register 5	0	ODDPD	0	When set powers down odd S/H, PGA
	1	EVENPD	0	When set powers down even S/H, PGA
	3	ADCPD	0	When set powers down ADC. Allows reduced power consumption without powering down the references which have a long time constant when switching on/off due to the external decoupling capacitors.
	4	VRLCDACPD	0	When set powers down 4-bit RLCDAC, setting the output to a high impedance state and allowing an external reference to be driven in on the VRLC/VBIAS pin.
	5	ADCREFPD	0	When set disables VRT, VRB buffers to allow external references to be used.
	6	VRXPD	0	When set disables VRX buffer to allow an external reference to be used.
	7	Not Used	0	Must be set to 0
Setup Register 6	4:0	Not Used	00000	Must be set to 0
	5	RLCEN	1	Reset Level Clamp Enable. When set Reset Level Clamping is enabled. The method of clamping is determined by CLAMPCTRL.
	6	CLAMPCTRL	0	0 = RLC switch is controlled directly from RSMP input pin: RSMP = 0: switch is open RSMP = 1: switch is closed  1 = RLC switch is controlled by logical combination of RSMP and VSMP. RSMP && VSMP = 0: switch is open RSMP && VSMP = 1: switch is closed
	7	Not Used	0	Must be set to 0

REGISTER	BIT NO	BIT NAME(S)	DEFAULT (BINARY)	DESCRIPTION
Offset DAC (Odd)	7:0	DACO[7:0]	10000000	Odd channel 8-bit offset DAC value (mV) = $255 \cdot (\text{DACR}[7:0] - 127.5) / 127.5$
Offset DAC (Even)	7:0	DACE[7:0]	10000000	Even channel 8-bit offset DAC value (mV) = $255 \cdot (\text{DACG}[7:0] - 127.5) / 127.5$
Offset DAC (Odd&Even)	7:0	DACOE[7:0]	10000000	A write to this register location causes both the odd and even offset DAC registers to be overwritten by the new value
PGA Gain LSB (Odd)	0	PGAO[0]	0	This register bit forms the LSB of the odd channel PGA gain code. PGA gain is determined by combining this register bit and the 8 MSBs contained in register address 28 hex.
	7:1	Not used	0000000	Must be set to 0
PGA Gain LSB (Even)	0	PGAE[0]	0	This register bit forms the LSB of the even channel PGA gain code. PGA gain is determined by combining this register bit and the 8 MSBs contained in register address 29 hex.
	7:1	Not used	0000000	Must be set to 0
PGA Gain LSB (Odd&Even)	0	PGAOE[0]	0	Writing a value to this location causes both the odd and even channel PGA LSB gain values to be overwritten by the new value.
	7:1	Not used	0000000	Must be set to 0
PGA gain MSBs (Odd)	7:0	PGAO[8:1]	00001100	Bits 8 to 1 of Odd channel PGA gain. Combined with Odd LSB register bit to form complete PGA gain code. This determines the gain of the Odd channel PGA according to the equation: Odd channel PGA gain (V/V) = $0.66 + \text{PGAO}[8:0] \times 7.34 / 511$
PGA gain MSBs (Even)	7:0	PGAE[8:1]	00001100	Bits 8 to 1 of Even channel PGA gain. Combined with Even LSB register bit to form complete PGA gain code. This determines the gain of the Even channel PGA according to the equation: Even channel PGA gain (V/V) = $0.66 + \text{PGAE}[8:0] \times 7.34 / 511$
PGA gain MSBs (Odd/Even)	7:0	PGAOE[8:1]	00000000	A write to this register location causes both the Odd and Even channel PGA MSB gain registers to be overwritten by the new value.

Table 6 Register Control Bits

APPLICATIONS INFORMATION

RECOMMENDED EXTERNAL COMPONENTS

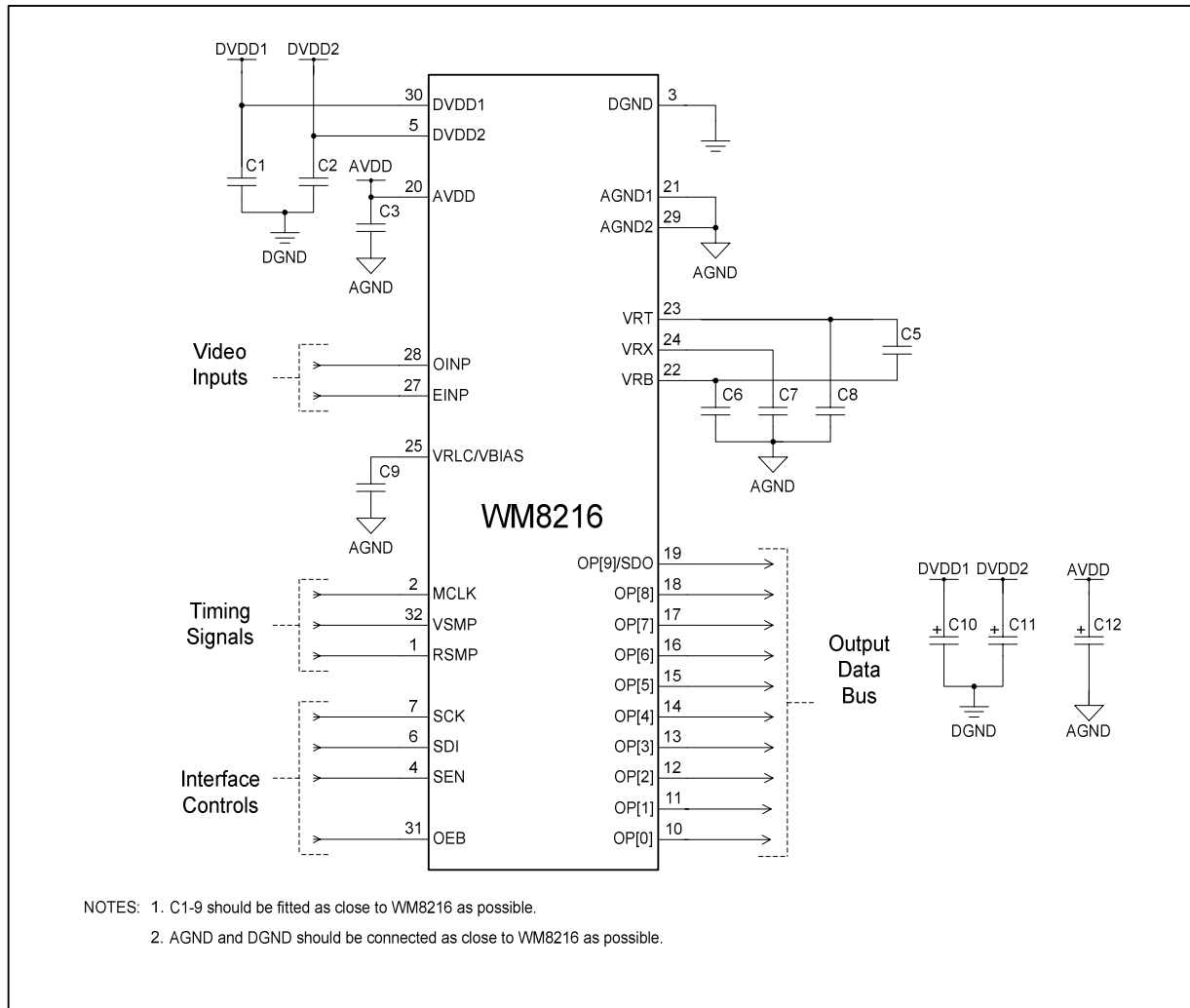


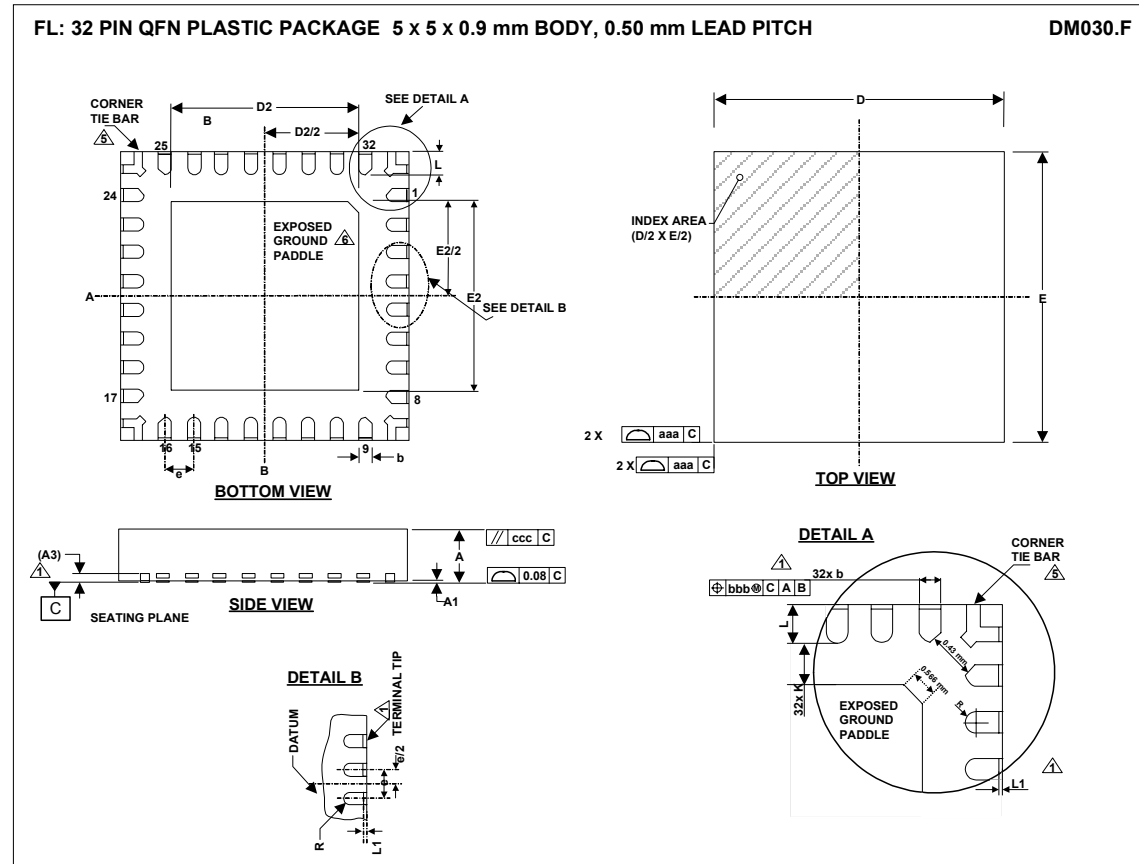
Figure 17 External Components Diagram

RECOMMENDED EXTERNAL COMPONENT VALUES

COMPONENT REFERENCE	SUGGESTED VALUE	DESCRIPTION
C1	100nF	De-coupling for DVDD1.
C2	100nF	De-coupling for DVDD2.
C3	100nF	De-coupling for AVDD.
C5	1µF	Ceramic de-coupling between VRT and VRB (non-polarised).
C6	100nF	De-coupling for VRB.
C7	100nF	De-coupling for VRX.
C8	100nF	De-coupling for VRT.
C9	100nF	De-coupling for VRLC.
C10	10µF	Reservoir capacitor for DVDD1.
C11	10µF	Reservoir capacitor for DVDD2.
C12	10µF	Reservoir capacitor for AVDD.

Table 7 External Components Descriptions

PACKAGE DIMENSIONS



Symbols	Dimensions (mm)			NOTE
	MIN	NOM	MAX	
A	0.85	0.90	1.00	
A1	0	0.02	0.05	
A3		0.2 REF		
b	0.18	0.23	0.30	1
D		5.00 BSC		
D2	3.2	3.3	3.4	2
E		5.00 BSC		
E2	3.2	3.3	3.4	2
e		0.5 BSC		
L	0.35	0.4	0.45	
L1			0.1	1
R	b(min)/2			
K	0.20			
<b>Tolerances of Form and Position</b>				
aaa		0.15		
bbb		0.10		
ccc		0.10		
REF:	JEDEC, MO-220, VARIATION VHHD-2			

- NOTES:
- DIMENSION b APPLIED TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP. DIMENSION L1 REPRESENTS TERMINAL PULL BACK FROM PACKAGE SIDE WALL. MAXIMUM OF 0.1mm IS ACCEPTABLE. WHERE TERMINAL PULL BACK EXISTS, ONLY UPPER HALF OF LEAD IS VISIBLE ON PACKAGE SIDE WALL DUE TO HALF ETCHING OF LEADFRAME.
  - FALLS WITHIN JEDEC, MO-220 WITH THE EXCEPTION OF D2, E2:  
D2, E2: LARGER PAD SIZE CHOSEN WHICH IS JUST OUTSIDE JEDEC SPECIFICATION
  - ALL DIMENSIONS ARE IN MILLIMETRES
  - THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE.
  - SHAPE AND SIZE OF CORNER TIE BAR MAY VARY WITH PACKAGE TERMINAL COUNT. CORNER TIE BAR IS CONNECTED TO EXPOSED PAD INTERNALLY.
  - REFER TO APPLICATION NOTE WAN\_0118 FOR FURTHER INFORMATION REGARDING PCB FOOTPRINTS AND QFN PACKAGE SOLDERING.

---

**IMPORTANT NOTICE**

Wolfson Microelectronics plc ("Wolfson") products and services are sold subject to Wolfson's terms and conditions of sale, delivery and payment supplied at the time of order acknowledgement.

Wolfson warrants performance of its products to the specifications in effect at the date of shipment. Wolfson reserves the right to make changes to its products and specifications or to discontinue any product or service without notice. Customers should therefore obtain the latest version of relevant information from Wolfson to verify that the information is current.

Testing and other quality control techniques are utilised to the extent Wolfson deems necessary to support its warranty. Specific testing of all parameters of each device is not necessarily performed unless required by law or regulation.

In order to minimise risks associated with customer applications, the customer must use adequate design and operating safeguards to minimise inherent or procedural hazards. Wolfson is not liable for applications assistance or customer product design. The customer is solely responsible for its selection and use of Wolfson products. Wolfson is not liable for such selection or use nor for use of any circuitry other than circuitry entirely embodied in a Wolfson product.

Wolfson's products are not intended for use in life support systems, appliances, nuclear systems or systems where malfunction can reasonably be expected to result in personal injury, death or severe property or environmental damage. Any use of products by the customer for such purposes is at the customer's own risk.

Wolfson does not grant any licence (express or implied) under any patent right, copyright, mask work right or other intellectual property right of Wolfson covering or relating to any combination, machine, or process in which its products or services might be or are used. Any provision or publication of any third party's products or services does not constitute Wolfson's approval, licence, warranty or endorsement thereof. Any third party trade marks contained in this document belong to the respective third party owner.

Reproduction of information from Wolfson datasheets is permissible only if reproduction is without alteration and is accompanied by all associated copyright, proprietary and other notices (including this notice) and conditions. Wolfson is not liable for any unauthorised alteration of such information or for any reliance placed thereon.

Any representations made, warranties given, and/or liabilities accepted by any person which differ from those contained in this datasheet or in Wolfson's standard terms and conditions of sale, delivery and payment are made, given and/or accepted at that person's own risk. Wolfson is not liable for any such representations, warranties or liabilities or for any reliance placed thereon by any person.

**ADDRESS:**

Wolfson Microelectronics plc  
Westfield House  
26 Westfield Road  
Edinburgh  
EH11 2QB

Tel :: +44 (0)131 272 7000

Fax :: +44 (0)131 272 7001

Email :: [sales@wolfsonmicro.com](mailto:sales@wolfsonmicro.com)